L Number	Hits	Search Text	DB	Time stamp
1	3697	integrated adj circuit adj die	USPAT;	2002/11/15 16:16
-		,g	US-PGPUB;	
1			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
2 .	1449	IC adj die	USPAT;	2002/11/15 16:16
2	1442	To adj die	US-PGPUB;	2002/11/15 10:10
			EPO; JPO;	
			DERWENT;	
	60/20		IBM_TDB	2002/11/15 16:17
3	58629	second adj surface	USPAT;	2002/11/15 16:17
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
4	68082	first adj surface	USPAT;	2002/11/15 16:18
1			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
5	48131	(first adj surface) and (second adj surface)	USPAT;	2002/11/15 16:18
			US-PGPUB;	
i			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
6	1386	passive adj component	USPAT;	2002/11/15 16:19
}			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
7	30	(passive adj component) and ((first adj surface) and (second adj	USPAT;	2002/11/15 16:19
		surface))	US-PGPUB;	
		"	EPO; JPO;	
			DERWENT;	
			IBM TDB	
8	4664	(integrated adj circuit adj die) (IC adj die)	USPĀT;	2002/11/15 16:19
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
9	4	((passive adj component) and ((first adj surface) and (second adj	USPAT;	2002/11/15 16:19
-	- 1	surface))) and ((integrated adj circuit adj die) (IC adj die))	US-PGPUB;	
			EPO; JPO;	
1			DERWENT;	
	ļ		IBM_TDB	
Ll			IDINI I DD	

L Number	Hits	Search Text	DB	Time stamp
1	3697	integrated adj circuit adj die	USPAT;	2002/11/15 16:16
•		,g	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
2	1449	IC adj die	USPAT;	2002/11/15 16:16
-	,	10 11,0 11	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
3	58629	second adj surface	USPĀT;	2002/11/15 16:17
	2002)		US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
4	68082	first adj surface	USPĀT;	2002/11/15 16:18
	00002	That day builded	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
5	48131	(first adj surface) and (second adj surface)	USPĀT;	2002/11/15 16:18
	40151	(mst day buriate) and (become degree and)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
-			IBM_TDB	
6	1386	passive adj component	USPĀT;	2002/11/15 16:19
١	1300	passive and composition	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
7	30	(passive adj component) and ((first adj surface) and (second adj	USPAT;	2002/11/15 16:19
′	50	surface))	US-PGPUB;	
		- Canada ()	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
8	4664	(integrated adj circuit adj die) (IC adj die)	USPĀT;	2002/11/15 16:19
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
9	4	((passive adj component) and ((first adj surface) and (second adj	USPAT;	2002/11/15 16:19
		surface))) and ((integrated adj circuit adj die) (IC adj die))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	